



10/8/10

**RELIABILITY MONITOR REPORT
FOR**

X3 Passive Chip Technology (PAC)

MAXIM Integrated Products

120 San Gabriel Dr.
Sunnyvale, CA 94086

**This Report was prepared by
Maxim Reliability Engineering**

Summary:

The data in the tables that follow was generated as the result of an on-going Process Reliability Monitor. The specific products in this process monitor are:

MAXEXP6ETE+

The calculated failure rate for devices using this process is:

FAILURE RATE: MTTF (YRS): 33796 QUANTITY: 240 FAILS: 0 FITS: 3.4

The parameters used to calculate this failure rate are as follows:

Cf: 60% Ea: 0.7 Tu: 25 °C

The reliability data follows and in this section is the detailed reliability data by stress. The reliability data section includes the latest data available. This report covers data between 10/1/2009 and 9/30/2010 .

Process Information:

Process Description: X3 Passive Chip Technology (PAC)

OPERATING LIFE

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	LOT NO.
HIGH TEMP OP LIFE	1014	MAXEXP6ETE+	135C	1000 HRS	80	0	SA6ZEZ108AC
HIGH TEMP OP LIFE	1014	MAXEXP6ETE+	135C	1000 HRS	80	0	SA6ZEZ201A
HIGH TEMP OP LIFE	1017	MAXEXP6ETE+	135C	1000 HRS	80	0	SA6ZEZ105AA
Total:						0	

STORAGE LIFE

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	LOT NO.
STORAGE LIFE	1014	MAXEXP6ETE+	150C	1000 HRS	80	0	SA6ZEZ108AC
STORAGE LIFE	1014	MAXEXP6ETE+	150C	1000 HRS	80	0	SA6ZEZ201A
STORAGE LIFE	1017	MAXEXP6ETE+	150C	1000 HRS	80	0	SA6ZEZ105AA
Total:						0	

TEMPERATURE CYCLE

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	LOT NO.
TEMP CYCLE, 5' RAMP, 10' DWELL	1014	MAXEXP6ETE+	-65C TO 150C	500 CYS	80	0	SA6ZEZ108AC
TEMP CYCLE, 5' RAMP, 10' DWELL	1014	MAXEXP6ETE+	-65C TO 150C	500 CYS	80	0	SA6ZEZ201A
TEMP CYCLE, 5' RAMP, 10' DWELL	1017	MAXEXP6ETE+	-65C TO 150C	500 CYS	80	0	SA6ZEZ105AA
Total:						0	

FAILURE RATE: MTTF (YRS): 33796 QUANTITY: 240 FAILS: 0 FITS: 3.4